

L Number	Hits	Search Text	DB	Time stamp
1	872	((uv or ultraviolet) near4 laser) near5 pulsed	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/15 14:01
2	35	((((uv or ultraviolet) near4 laser) near5 pulsed) and inspecti\$ and diffus\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/15 13:57
3	12	((((uv or ultraviolet) near4 laser) near5 pulsed) same inspecti\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/15 14:11
4	78	((((uv or ultraviolet) near4 laser) near5 pulsed) and inspecti\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/15 14:05
5	3	((((uv or ultraviolet) near4 laser) near5 pulsed) and inspecti\$) and microlithography	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/15 14:07
6	86	inspection near14 microlithography	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/15 14:16
7	0	((((uv or ultraviolet) near4 laser) near5 pulsed) and (inspection near14 microlithography)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/15 14:07
8	57	(inspection near14 microlithography) and laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/15 14:08
9	0	((((uv or ultraviolet) near4 laser) near5 pulsed) near7 inspecti\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/15 14:28
10	56	((uv or ultraviolet) near4 laser) near7 inspecti\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/15 14:12
11	76	(inspection near14 microlithography) and (mask or wafer or reticle)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/15 14:16
12	983	(uv or ultraviolet) near7 inspecti\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/15 14:29

13	5861	(uv or ultraviolet) near7 (microlithograph\$ or photolithograph\$ or lithograph\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/15 14:29
14	55	((uv or ultraviolet) near7 inspecti\$) and ((uv or ultraviolet) near7 (microlithograph\$ or photolithograph\$ or lithograph\$))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/15 14:29